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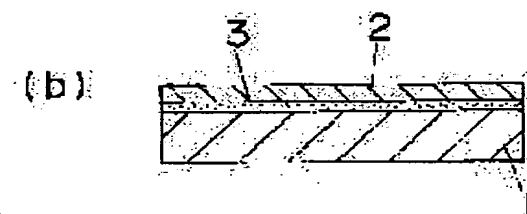
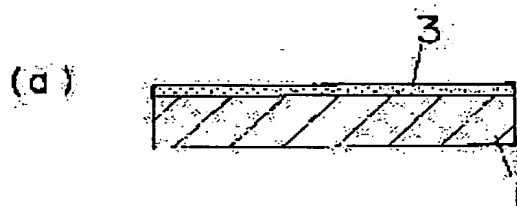
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(54) MOLDINGS WITH METAL COATING AND MANUFACTURING METHOD THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To provide moldings with a metal coating which are formed with the metal coating effectively adhering to the surface of resin moldings without impairing the characteristics of a resin as a constituent of the resin moldings.

SOLUTION: The moldings with a metal coating are constituted of the resin moldings 1 and the metal film 2 applied to the surface of the former. An intermediate film 3 containing a resin showing higher adhesive properties to the metal film 2 than the adhesive properties between the resin of the resin moldings 1 and the metal film 2, is formed with a thickness of 5 μ m or less between the resin moldings 1 and the metal film 2. In addition, the adhesive properties of the metal film 2 to the surface of the resin moldings 1 can be enhanced by the intermediate film 3 containing the resin showing higher adhesive properties to the metal film 2. The intermediate film 3 is set to be as thin as 5 μ m or less, so that the characteristics of the resin moldings 1 are not impaired by the intermediate film 3.



- 1 樹脂成形体
- 2 金属膜
- 3 中間膜

LEGAL STATUS

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